## Designer's™ Data Sheet

# **Insulated Gate Bipolar Transistor**

### N-Channel Enhancement-Mode Silicon Gate

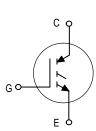
This Insulated Gate Bipolar Transistor (IGBT) uses an advanced termination scheme to provide an enhanced and reliable high voltage—blocking capability. Short circuit rated IGBT's are specifically suited for applications requiring a guaranteed short circuit withstand time such as Motor Control Drives. Fast switching characteristics result in efficient operation at high frequencies.

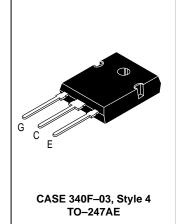
- Industry Standard High Power TO–247 Package with Isolated Mounting Hole
- High Speed E<sub>off</sub>: 60 μJ per Amp typical at 125°C
- High Short Circuit Capability 10 μs minimum
- Robust High Voltage Termination
- Robust RBSOA



Motorola Preferred Device

IGBT IN TO-247
30 A @ 90°C
50 A @ 25°C
600 VOLTS
SHORT CIRCUIT RATED





#### **MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Rating		Value	Unit		
Collector–Emitter Voltage	VCES	600	Vdc		
Collector–Gate Voltage (R <sub>GE</sub> = 1.0 MΩ)	VCGR	600	Vdc		
Gate-Emitter Voltage — Continuous	VGE	±20	Vdc		
Collector Current — Continuous @ T <sub>C</sub> = 25°C — Continuous @ T <sub>C</sub> = 90°C — Repetitive Pulsed Current (1)	I <sub>C25</sub> I <sub>C90</sub> I <sub>CM</sub>	50 30 100	Adc Apk		
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	202 1.61	Watts W/°C		
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C		
Short Circuit Withstand Time (V <sub>CC</sub> = 360 Vdc, V <sub>GE</sub> = 15 Vdc, T <sub>J</sub> = 25°C, R <sub>G</sub> = 20 $\Omega$ )	t <sub>SC</sub>	10	μs		
Thermal Resistance — Junction to Case – IGBT — Junction to Ambient	R <sub>θ</sub> JC R <sub>θ</sub> JA	0.62 45	°C/W		
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C		
Mounting Torque, 6–32 or M3 screw	10	10 lbf•in (1.13 N•m)			

<sup>(1)</sup> Pulse width is limited by maximum junction temperature.

**Designer's Data for "Worst Case" Conditions** — The Designer's Data Sheet permits the design of most circuits entirely from the information presented. SOA Limit curves — representing boundaries on device characteristics — are given to facilitate "worst case" design.

Preferred devices are Motorola recommended choices for future use and best overall value.



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## **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Cha	racteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector–to–Emitter Breakdown Voltage (VGE = 0 Vdc, I <sub>C</sub> = 250 μAdc) Temperature Coefficient (Positive)		BVCES	600 —	 870	_	Vdc mV/°C
Emitter-to-Collector Breakdown Voltage (V <sub>GE</sub> = 0 Vdc, I <sub>EC</sub> = 100 mAdc)		BVECS	25	_	_	Vdc
Zero Gate Voltage Collector Current  (VCE = 600 Vdc, VGE = 0 Vdc)  (VCE = 600 Vdc, VGE = 0 Vdc, TJ = 125°C)		ICES	=	_	100 2500	μAdc
Gate-Body Leakage Current (VGE = ± 20 Vdc, VCE = 0 Vdc)		IGES	_	_	250	nAdc
ON CHARACTERISTICS (1)		•				
Collector-to-Emitter On-State Volta (V <sub>GE</sub> = 15 Vdc, I <sub>C</sub> = 15 Adc) (V <sub>GE</sub> = 15 Vdc, I <sub>C</sub> = 15 Adc, T <sub>J</sub> = (V <sub>GE</sub> = 15 Vdc, I <sub>C</sub> = 30 Adc)		VCE(on)	=======================================	2.20 2.10 2.60	2.90 — 3.45	Vdc
Gate Threshold Voltage (V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1 mAdc) Threshold Temperature Coefficien	nt (Negative)	VGE(th)	4.0 —	6.0 10	8.0 —	Vdc mV/°C
Forward Transconductance (VCE =	10 Vdc, I <sub>C</sub> = 30 Adc)	9fe	_	15	_	Mhos
DYNAMIC CHARACTERISTICS		•	•	•		
Input Capacitance	(V <sub>CE</sub> = 25 Vdc, V <sub>GE</sub> = 0 Vdc, f = 1.0 MHz)	C <sub>ies</sub>	_	4280	_	pF
Output Capacitance		C <sub>oes</sub>	_	275	_	
Transfer Capacitance	,	C <sub>res</sub>	_	19	_	
SWITCHING CHARACTERISTICS (1	1)	•				
Turn-On Delay Time	$(V_{CC}=360~Vdc,~I_{C}=30~Adc,~V_{GE}=15~Vdc,~L=300~\mu H~R_{G}=20~\Omega,~T_{J}=25^{\circ}C)$ Energy losses include "tail"	<sup>t</sup> d(on)	_	76	_	ns
Rise Time		t <sub>r</sub>	-	80	_	
Turn-Off Delay Time		<sup>t</sup> d(off)	_	348	_	
Fall Time		t <sub>f</sub>	_	188	_	
Turn-Off Switching Loss		E <sub>off</sub>	_	0.98	1.28	mJ
Turn-On Delay Time	(V <sub>CC</sub> = 360 Vdc, I <sub>C</sub> = 30 Adc, V <sub>GE</sub> = 15 Vdc, L = 300 μH R <sub>G</sub> = 20 Ω, T <sub>J</sub> = 125°C) Energy losses include "tail"	<sup>t</sup> d(on)	_	73	_	ns
Rise Time		t <sub>r</sub>	_	95	_	
Turn-Off Delay Time		<sup>t</sup> d(off)	_	394	_	
Fall Time		t <sub>f</sub>	_	418	_	
Turn-Off Switching Loss		E <sub>off</sub>	_	1.90	_	mJ
Gate Charge	(V <sub>CC</sub> = 360 Vdc, I <sub>C</sub> = 30 Adc, V <sub>GE</sub> = 15 Vdc)	QT	_	150	_	nC
		Q <sub>1</sub>	_	30	_	
		Q <sub>2</sub>	_	45	_	
NTERNAL PACKAGE INDUCTANC	E					
Internal Emitter Inductance (Measured from the emitter lead 0.25" from package to emitter bond pad)		LE		13		nH

#### TYPICAL ELECTRICAL CHARACTERISTICS

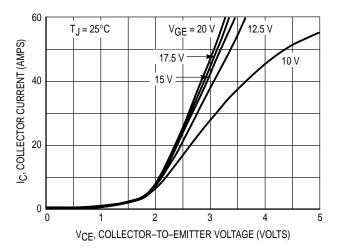


Figure 1. Output Characteristics, T<sub>J</sub> = 25°C

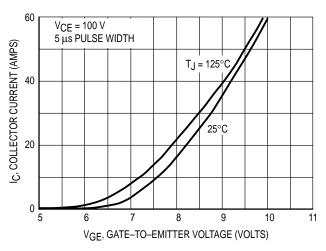


Figure 3. Transfer Characteristics

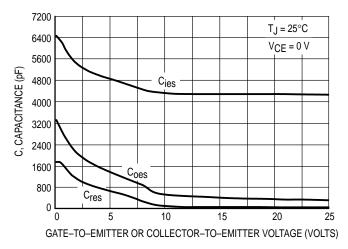


Figure 5. Capacitance Variation

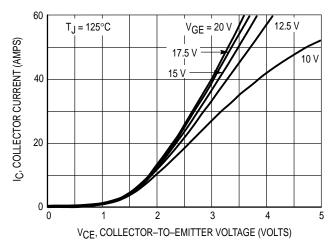


Figure 2. Output Characteristics, T<sub>J</sub> = 125°C

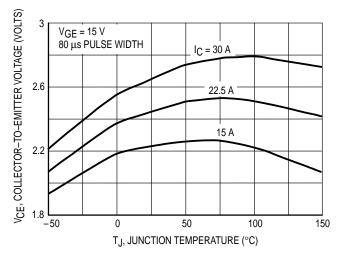


Figure 4. Collector-to-Emitter Saturation Voltage versus Junction Temperature

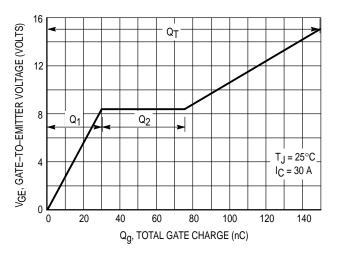


Figure 6. Gate-to-Emitter Voltage versus
Total Charge

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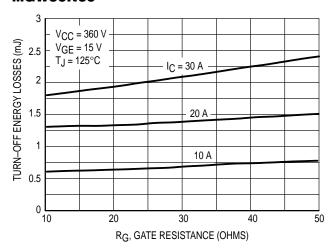


Figure 7. Turn–Off Losses versus
Gate Resistance

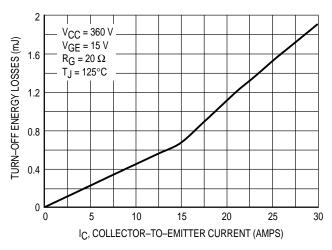


Figure 9. Turn-Off Losses versus Collector-to-Emitter Current

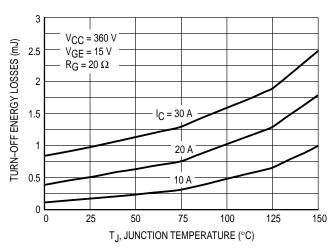


Figure 8. Turn-Off Losses versus Junction Temperature

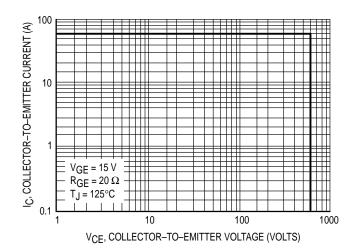
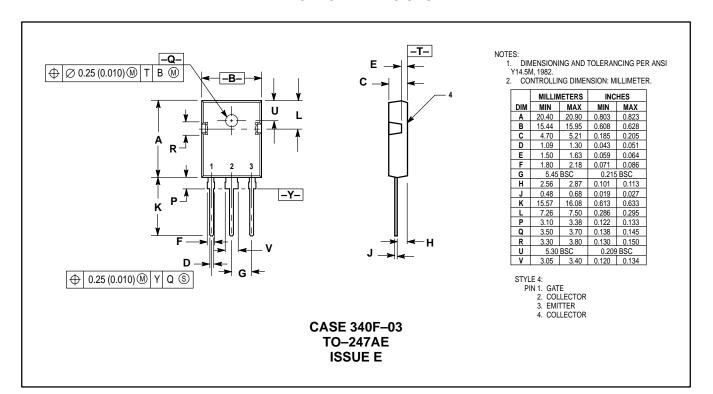


Figure 10. Reverse Biased Safe Operating Area

#### **PACKAGE DIMENSIONS**



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